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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 070679-0264

103425038

To the Director of the U. S. Patent and Trademark Office. Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Hye-Young LEE

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): June 27, 2007

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: HYNIX SEMICONDUCTOR INC.

Internal Address:

Address: San 136-1, Ami-ri, Bubal-eub, Ichon-shi,
Kyongki-do, 467-860, Republic of KOREA

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application or patent number(s):

A. Patent Application No(s).

☒ This document is being filed together with a new application

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

Phone Number: 202.756.8000

Fax Number: 202.756.8087

Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)nt

8. Payment Information:

- a. Credit Card Last 4 Numbers 500417
Expiration Date 06/01/07
b. Deposit Account Number 500417
Authorized User Name

9. Signature.

Stephen A. Becker, 26, 527

Signature

June 29, 2007

Name and Registration No. of Person Signing

Total number of pages including cover sheet, attachments and documents: 2

OMB No. 0651-0027 (exp. 6/30/2008)

PATENT
REEL: 019546 FRAME: 0091

(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

LEE, Hye-Young

who has made a certain new and useful invention, hereby sells, assigns and transfers unto
Hynix Semiconductor Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

DELAY LOCKED LOOP OF SEMICONDUCTOR DEVICE

AND METHOD FOR DRIVING THE SAME

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____, or

(b) for which an application for United States Letters Patent was executed on _____

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

Hye-young Lee

June 27, 2007

Name: **LEE, Hye-Young**

PATENT

RECORDED: 06/29/2007

REEL: 019546 FRAME: 0092